Application Serial No. 09/998,467

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claim 1 has been amended as follows:

1. (Amended) A semiconductor device in which bumps formed on a surface of a semiconductor chip and leads of a lead frame are set to face each other and all simultaneously thermally bonded together, wherein:

each one said bumps on said surface of said semiconductor chip is provided with a recess in a surface thereof that faces each of said leads of said lead frame, the recess being in the shape of an inverted truncated pyramid and comprising guide-surfaces that are inclined surfaces and are formed between a bottom of said recess and opening edges of said recess; and

each of said leads of said lead frame is provided with a projection formed at one end thereof so as to be bonded to each of said bumps, said projection being formed with guided-surfaces that are inclined surfaces.

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